



February 15, 2023

Mr. Richard Revesz
OIRA Administrator
Office of Information and Regulatory Affairs
Office of Management and Budget
Washington, DC 20503

Dear Mr. Revesz,

Pursuant to Office of Management and Budget (OMB) procedures established at 5 CFR Part 1320, Controlling Paperwork Burdens on the Public, I request an emergency clearance of the attached package for the Creating Helpful Incentives to Produce Semiconductors (CHIPS) Statement of Interest Information Collection.

The Administration and Congress have identified the low U.S. production of semiconductor chips as a national security risk that must be addressed as quickly as possible. As stated in the August 9, 2022 *FACT SHEET: CHIPS and Science Act Will Lower Costs, Create Jobs, Strengthen Supply Chains, and Counter China* (avail. at <https://www.whitehouse.gov/briefing-room/statements-releases/2022/08/09/fact-sheet-chips-and-science-act-will-lower-costs-create-jobs-strengthen-supply-chains-and-counter-china/>), semiconductor chip technology “forms the foundation of everything from automobiles to household appliances to defense systems. America invented the semiconductor, but today produces about 10 percent of the world’s supply—and none of the most advanced chips. Instead, we rely on East Asia for 75 percent of global production. The CHIPS and Science Act will unlock hundreds of billions more in private sector semiconductor investment across the country, including production essential to national defense and critical sectors.”

In order to help address the risk posed by this low U.S. production, Congress passed the CHIPS for America Act of the William M. (Mac) Thornberry National Defense Authorization Act for Fiscal Year 2021 (Pub. L. 116-283, referred to as “the CHIPS Act” or “the Act”), as amended by the CHIPS and Science Act of 2022 (Division A of Pub. L. 117-167), codified in relevant part at 15 U.S.C. 4652, 4654, and 4656. The Act tasks the Secretary of Commerce with establishing a semiconductor incentives program to support the domestic production of semiconductors. The program will provide financial assistance awards to incentivize investment in facilities and equipment in the United States for semiconductor fabrication, assembly, testing, advanced packaging, and research and development, thereby increasing U.S. economic and national security by supporting a sustainable, competitive domestic semiconductor industry. Because both Congress and the Administration have identified the current low U.S. production of semiconductor chips as a matter of national security and defense, Secretary Raimondo is


implementing this program on an expedited timeline to meet the identified U.S. economic and national security needs.

Thus, emergency approval of the CHIPS Statement of Interest (SOI) is essential to prevent public harm under 5 C.F.R. 1320.13(a)(2). Normal clearance would delay implementation of the program, thereby extending the national security and economic risk presented by the U.S. low semiconductor chip production.

Your consideration of this matter is greatly appreciated. Should any questions arise regarding this request, please contact Elizabeth Reinhart, NIST Management Analyst, at Elizabeth.Reinhart@nist.gov.

Sincerely,

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Laurie E. Locascio, Ph.D.

Under Secretary of Commerce for Standards and Technology &
Director, National Institute of Standards and Technology

cc: Hon. Gina R. Raimondo